



SF2DDF-SF2JDF

Product Summary (@ T_A = +25°C)

V _{RRM} (V)	I ₀ (A)	V _F Max (V)	I _R Max (μA)
600	2	1.7	5
400	2	1.3	5
200	2	1.1	5

Description and Applications

The SF2xDF is a rectifier packaged in the D-FLAT package and is suited as a boost diode in power factor correction circuitry. For use in secondary rectification and freewheeling for superfast switching speed AC-DC and DC-DC converters in high-temperature conditions for consumer applications.

- DC-DC Converters
- AC-DC Adaptors/Chargers
- Inverters

Mechanical Data

- Case: D-FLAT
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Polarity: Cathode Band
- Weight: 0.0354 grams (Approximate)

Top View

1 0 2 CATHODE ANODE

Schematic View

Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
SF2JDF-13	Commercial	D-FLAT	10,000/Tape & Reel
SF2GDF-13	Commercial	D-FLAT	10,000/Tape & Reel
SF2DDF-13	Commercial	D-FLAT	10,000/Tape & Reel

D-FLAT

Notes: 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.

2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information





E2x = Product Type Marking Code (ie. E2J for SF2JDF, E2G for SF2GDF, E2D for SF2DDF))'' = Manufacturers' Code Marking YWW = Date Code Marking Y = Last Digit of Year (ex: 9 for 2019) WW = Week Code (01 to 53) AB = Foundry and Assembly Code

2.0A SURFACE MOUNT SUPER-FAST RECTIFIER

Features and Benefits

- Low Profile, Small Form Factor Package
- Low Leakage Current
- Glass Passivated for High Reliability
- Superfast Recovery Times for High Efficiency
- Low Forward Voltage, Low Power Loss
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)



Maximum Ratings and Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For ca	pacitive	load, derate	current b	y 20%.

Characteristic	Symbol	SF2DDF	SF2GDF	SF2JDF	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	400	600	V
Average Rectified Output Current @T _T = +88°C (Note 5)	lo		2.0		А
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	50			А
Maximum Instantaneous Forward Voltage @ I _F = 2A	VF	1.1	1.3	1.7	V
Maximum DC Reverse Current @ T _A = +25°C at Rated DC Blocking Voltage @ T _A = +100°C (Note 7)	I _R	5 100		μA	
Typical Total Capacitance (Note 8)	CT	50			pF
Maximum Reverse Recovery Time (Note 9)	t _{RR}	35 35			ns

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Terminal (Note 6)	R _{θJT}	30	°C/W
Typical Thermal Resistance Junction to Ambient (Note 6)	R _{ÐJA}	56	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

5.Device mounted on FR-4 substrate, 1" x 1", 2oz, single-sided, PCBs with 0.1" x 0.15" copper pad.
6. Device mounted on FR-4 substrate, 0.4" x 0.5", 2oz, single-sided, PCBs with 0.2" x 0.25" copper pad.
7. Short duration pulse test used to minimize self-heating effect.
8. Measured at 1.0MHZ and applied reverse voltage of 4.0V DC.
9. Measured with 0.5 h 4.0 k 0.00 conditioned on the device of the device Notes:

9. Measured with I_F=0.5A, I_R=1A, I_{RR}=0.25A.



SF2DDF-SF2JDF





1

10



PERCENTAGE RATED PEAK REVERSE VOLTAGE (%)

Fig 4. Typical Reverse Charactersitcs



Fig 6. Reverse Recovery Time Characteristic and Test Circuit

0

100



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.



D-FLAT				
Dim	Min	Max		
Α	0.90	1.10		
b	1.25	1.65		
С	0.10	0.40		
D	2.25	2.95		
Е	3.95	4.60		
k	2.80	-		
HE	5.00	5.60		
L	0.50	1.30		
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



D-FLAT

D-FLAT

Dimensions	Value (in mm)
С	4.65
G	2.80
X	1.85
X1	6.50
Y	1.70



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